



Material Content Data Sheet



Sales Product Name		TLE7270-2E		Issued		20. July 2018		
MA#		MA000970646						
Package		PG-SSOP-14-2		Weight*		83.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.717	2.06	2.06	20645	20645
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		414	
	non noble metal	iron	7439-89-6	0.689	0.83		8287	
wire	non noble metal	copper	7440-50-8	27.978	33.65	34.53	336472	345277
	noble metal	gold	7440-57-5	0.136	0.16	0.16	1632	1632
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1196
plastics	plastics	epoxy resin	-	4.573	5.50		54996	
		inorganic material	silicondioxide	60676-86-0	45.034	54.17	59.79	541596
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11739	11739
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9232	9232
glue	plastics	epoxy resin	-	0.285	0.34		3422	
		noble metal	silver	7440-22-4	0.854	1.03	1.37	10265
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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